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mixing a thermally conductive filler material into said base thermoplastic polymer matrix to form a thermally conductive composite material;

injection molding a part from said thermally conductive composite material into a net shape molded configuration;

providing a contact surface for flush thermal communication with a heat generating object; and

applying a metallic coating over said part.

REMARKS

This amendment is responsive to the official action dated November 25, 2002.

Claims 9 and 10 were pending in the application. Claims 9 and 10 were rejected. No claims were allowed by the Examiner.

By way of this amendment, Claim 9 has been amended. Claim 10 remains unchanged.

Accordingly, Claims 9 and 10 are currently pending.

I. REJECTION OF CLAIMS UNDER 35 USC 102

Claims 9 and 10 were rejected under 35 USC 102(b), as being anticipated by US Statutory Registration No. H526 (Miller). The invention in Miller provides a box for housing sensitive electronic equipment formed from Kevlar in an epoxy resin with a copper EMI reflective layer applied thereto. Specifically, however, the Miller reference discloses the formation of the substrate box using a compression molding or pultrusion method where layers of Kevlar fibers are layed up with coatings of epoxy resin and pressed into the desired shape as the epoxy cures. Specifically, Miller identifies injection molding as being inappropriate for use in the disclosed invention (Col. 7, lines 14-22). The reference to fabrication using injection molding refers to first forming a structural foam core using an injection molding process and then laminating layers of fiber mats and epoxy resins over the foam structural core. In addition, there is no disclosure within the Miller reference describing the injection molding of a thermoplastic base resin reinforced with structural fibers nor is there any disclosure regarding an